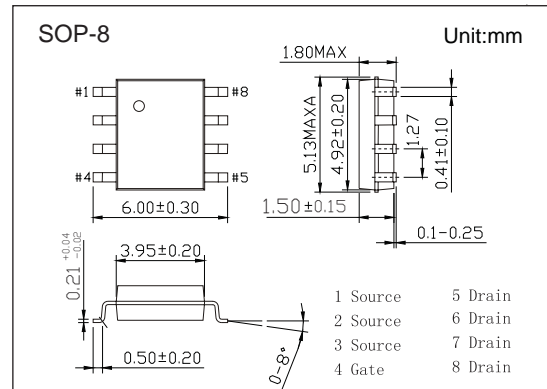
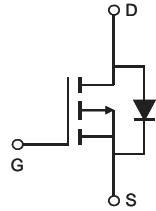


## P-channel MOSFET

## 2KJ7008

## ■ Features

- $V_{DS} = -40V$
- $I_D = -13 A$
- $R_{DS(on)} < 15m\Omega @ V_{GS} = -10V$
- $R_{DS(on)} < 18m\Omega @ V_{GS} = -4.5V$
- High density cell design for ultra low  $R_{dson}$
- Fully characterized avalanche voltage and current
- Excellent package for good heat dissipation

■ Absolute Maximum Ratings ( $T_A = 25^\circ C$  unless otherwise noted)

Parameter	Symbol	Rating	Unit
Drain-Source Voltage	$V_{DS}$	-40	V
Gate-Source Voltage	$V_{GS}$	$\pm 20$	
Continuous Drain Current	$I_D$	-13	A
Pulsed Drain Current (Note 1)	$I_{DM}$	-50	
Maximum Power Dissipation	$P_D$	2.5	W
Thermal Resistance, Junction- to-Ambient (Note 2)	$R^{\theta}_{JA}$	50	$^\circ C/W$
Junction Temperature	$T_J$	150	$^\circ C$
Junction Storage Temperature Range	$T_{stg}$	-55 to 150	

Notes:

1. Repetitive Rating: Pulse width limited by maximum junction temperature.
2. Surface Mounted on FR4 Board,  $t \leq 10$  sec.

## P-channel MOSFET

## 2KJ7008

■ Electrical Characteristics ( $T_A = 25^\circ\text{C}$  unless otherwise noted)

Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
<b>Off Characteristics</b>						
Drain-Source Breakdown Voltage	$V_{DSS}$	$I_D = -250\mu\text{A}$ , $V_{GS} = 0\text{V}$	-40			V
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS} = -40\text{V}$ , $V_{GS} = 0\text{V}$			-1	$\mu\text{A}$
Gate-Body Leakage Current	$I_{GSS}$	$V_{DS} = 0\text{V}$ , $V_{GS} = \pm 20\text{V}$			$\pm 100$	nA
<b>On Characteristics (Note 3)</b>						
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}$ , $I_D = -250\mu\text{A}$	-1.3	-2	-2.5	V
Static Drain-Source On-Resistance	$R_{DS(on)}$	$V_{GS} = -10\text{V}$ , $I_D = -12\text{A}$		12	15	$\text{m}\Omega$
Forward Transconductance	$g_{FS}$	$V_{DS} = -15\text{V}$ , $I_D = -10\text{A}$	35			S
<b>Dynamic Characteristics (Note 4)</b>						
Input Capacitance	$C_{iss}$	$V_{GS} = 0\text{V}$ , $V_{DS} = -20\text{V}$ , $f = 1\text{MHz}$		2800		pF
Output Capacitance	$C_{oss}$			320		
Reverse Transfer Capacitance	$C_{rss}$			220		
<b>Switching Characteristics (Note 4)</b>						
Turn-On Delay Time	$t_{d(on)}$	$V_{DS} = -20\text{V}$ , $R_L = 2\Omega$ $V_{GS} = -10\text{V}$ , $R_{GEN} = 6\Omega$		11		ns
Turn-On Rise Time	$t_r$			75		
Turn-Off Delay Time	$t_{d(off)}$			89		
Turn-Off Fall Time	$t_f$			35		
Total Gate Charge	$Q_g$	$V_{DS} = -20\text{V}$ , $I_D = -12\text{A}$ , $V_{GS} = -10\text{V}$		40		nC
Gate Source Charge	$Q_{gs}$			6		
Gate Drain Charge	$Q_{gd}$			12		
<b>Drain-Source Diode Characteristics (Note 3)</b>						
Diode Forward Voltage	$V_{SD}$	$I_{SD} = -12\text{A}$ , $V_{GS} = 0\text{V}$			-1.2	V
Diode Forward Current	$I_S$				-13	A

Notes:

1. Pulse Test: Pulse Width  $\leq 300\mu\text{s}$ , Duty Cycle  $\leq 2\%$ .
2. Guaranteed by design, not subject to production

## ■ Marking

Marking	J7008 KC****
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# P-channel MOSFET

## 2KJ7008

### Typical Electrical and Thermal Characteristics

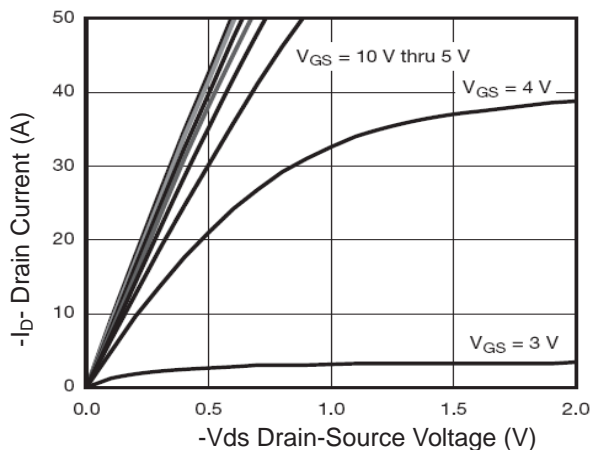


Figure 1 Output Characteristics

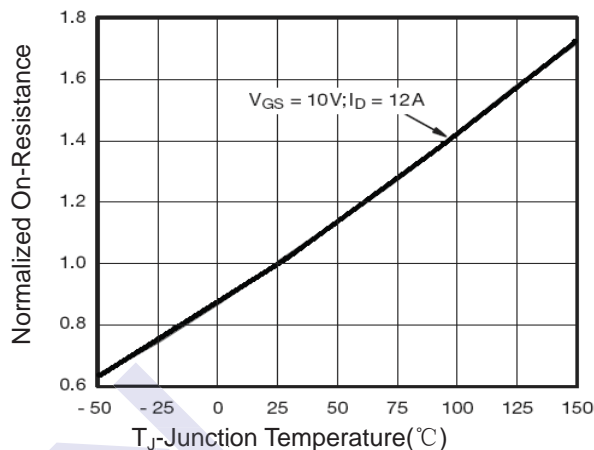


Figure 4  $R_{dson}$ -Junction Temperature

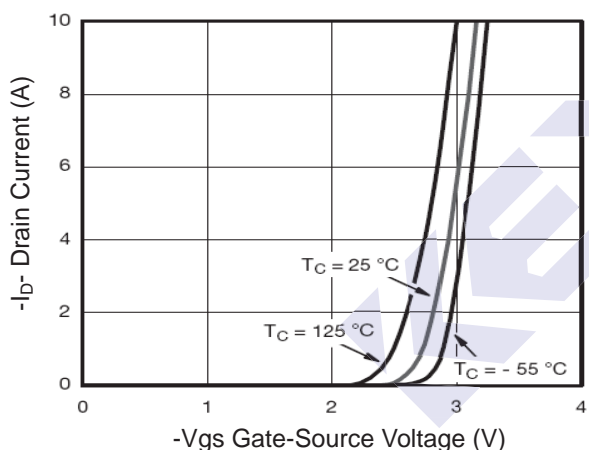


Figure 2 Transfer Characteristics

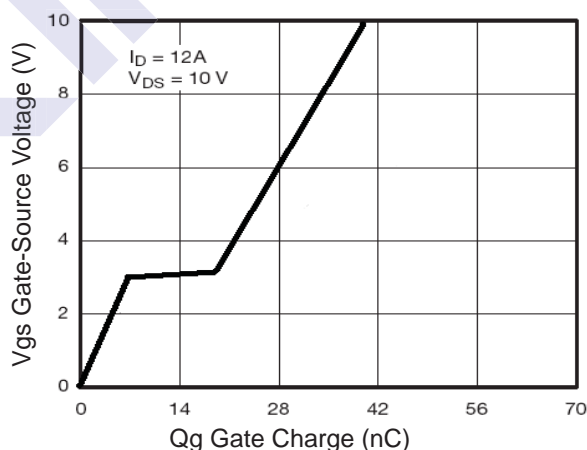


Figure 5 Gate Charge

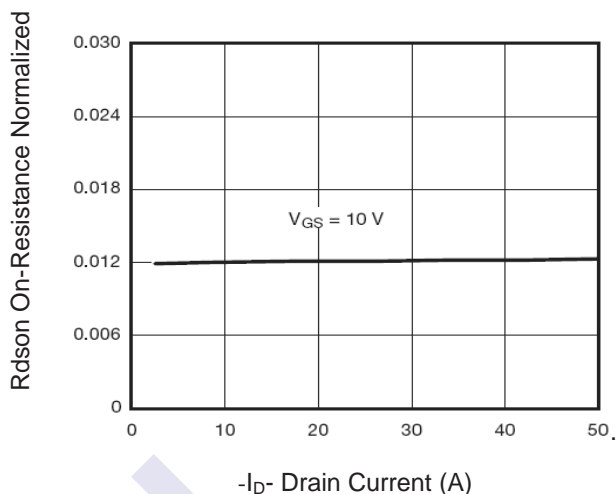


Figure 3  $R_{dson}$ - Drain Current

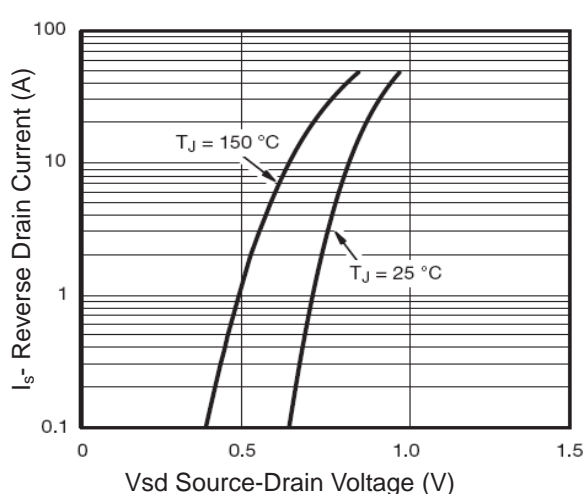


Figure 6 Source- Drain Diode Forward

P-channel MOSFET

2KJ7008

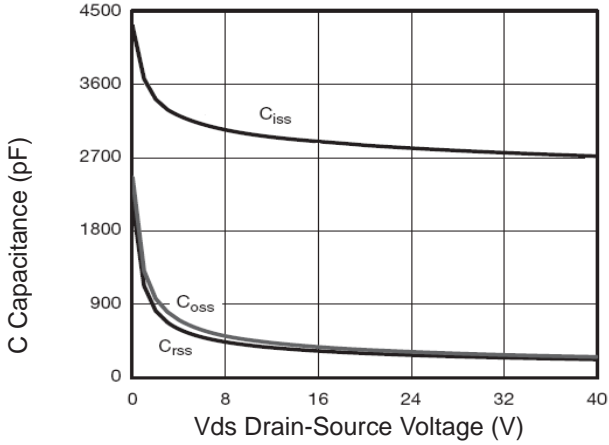


Figure 7 Capacitance vs Vds

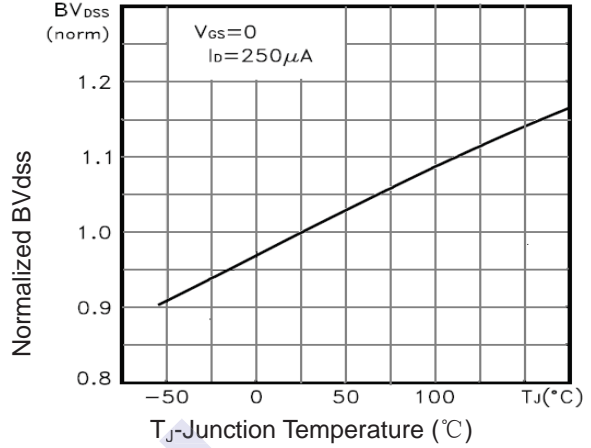


Figure 9  $BV_{DSS}$  vs Junction Temperature

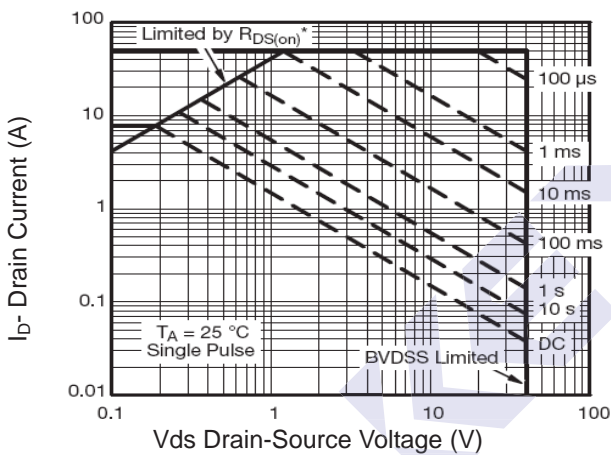


Figure 8 Safe Operation Area

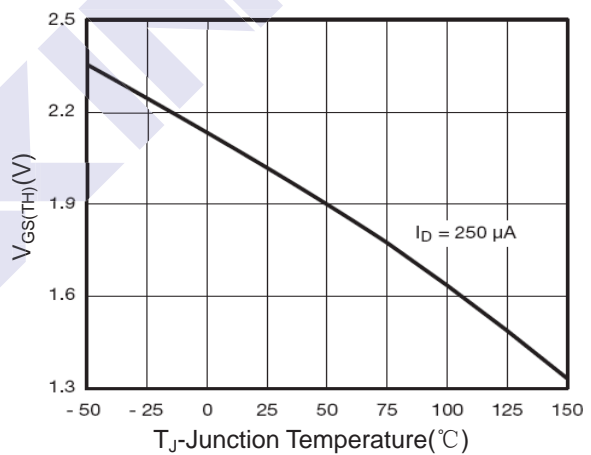


Figure 10  $V_{GS(th)}$  vs Junction Temperature

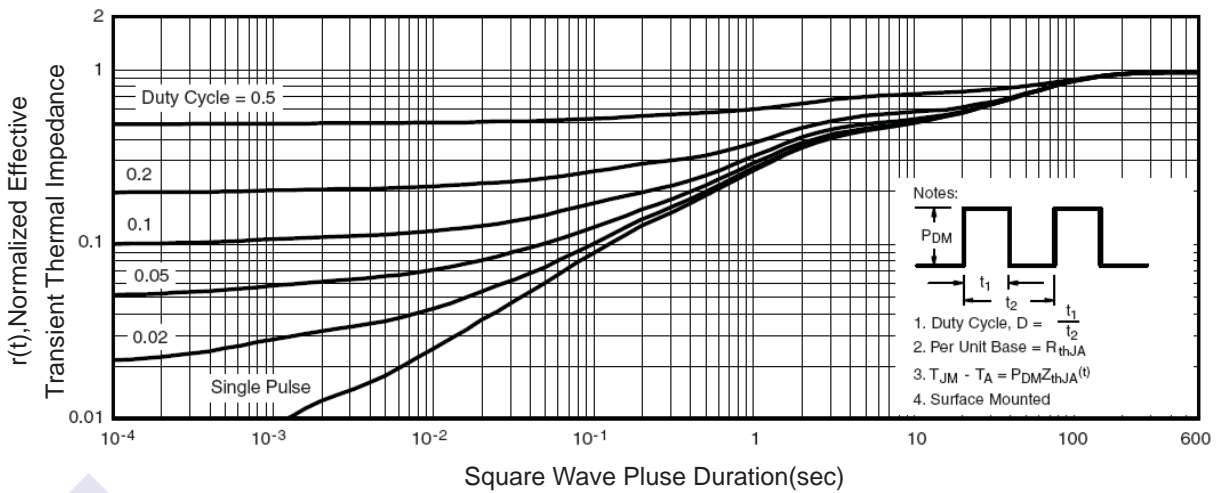


Figure 11 Normalized Maximum Transient Thermal Impedance